



#### PNP MEDIUM POWER TRANSISTORS IN SOT89

#### **Features**

- BV<sub>CEO</sub> > -45V, -60V & -80V
- I<sub>C</sub> = -1A Continuous Collector Current
- I<sub>CM</sub> = -2A Peak Pulse Current
- Low Saturation Voltage V<sub>CE(SAT)</sub> < -500mV @ -0.5A</li>
- Gain Groups 10 and 16
- Complementary NPN Types: BCX54, 55 and 56
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

#### **Mechanical Data**

- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound;
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Leads; Solderable per MIL-STD-202 Method 208 (3)
- Weight: 0.052 grams (Approximate)

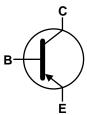
### **Applications**

- Medium Power Switching or Amplification Applications
- AF Driver and Output Stages

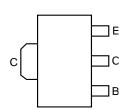








Device Symbol



Top View Pin-Out

### Ordering Information (Notes 4 & 5)

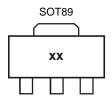
Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
BCX51TA	AEC-Q101	AA	7	12	1,000
BCX51-13R	AEC-Q101	AA	13	12	4,000
BCX5110TA	AEC-Q101	AC	7	12	1,000
BCX5116TA	AEC-Q101	AD	7	12	1,000
BCX5116TC	AEC-Q101	AD	13	12	4,000
BCX52TA	AEC-Q101	AE	7	12	1,000
BCX5210TA	AEC-Q101	AG	7	12	1,000
BCX5216TA	AEC-Q101	AM	7	12	1,000
BCX5216QTA	Automotive	AM	7	12	1,000
BCX53TA	AEC-Q101	AH	7	12	1,000
BCX5310TA	AEC-Q101	AK	7	12	1,000
BCX5316TA	AEC-Q101	AL	7	12	1,000
BCX5316TC	AEC-Q101	AL	13	12	4,000
BCX5316-13R	AEC-Q101	AL	13	12	4,000
BCX5110TC	AEC-Q101	AC	13	12	4,000
BCX51TC	AEC-Q101	AA	13	12	4,000
BCX5210TC	AEC-Q101	AG	13	12	4,000
BCX5216TC	AEC-Q101	AM	13	12	4,000
BCX52TC	AEC-Q101	AE	13	12	4,000
BCX5310TC	AEC-Q101	AK	13	12	4,000
BCX53TC	AEC-Q101	AH	13	12	4,000
BCX5316QTA	Automotive	Refer to http://diodes.com/datasheets/BCX5316Q.pdf			

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.



### **Marking Information**



xx = Product Type Marking Code, as follows:

 BCX51
 = AA
 BCX52
 = AE
 BCX53
 = AH

 BCX5110
 = AC
 BCX5210
 = AG
 BCX5310
 = AK

 BCX5116
 = AD
 BCX5216
 = AM
 BCX5316
 = AL

## Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	BCX51	BCX52	BCX53	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-45	-60	-100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-45	-60	-80	V
Emitter-Base Voltage	$V_{EBO}$	-5		V	
Continuous Collector Current	Ic	-1			Α
Peak Pulse Collector Current	I <sub>CM</sub>	-2			
Continuous Base Current	I <sub>B</sub>	-100		mA	
Peak Pulse Base Current	I <sub>BM</sub>		-200		

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
	(Note 6)		1		
Power Dissipation	(Note 7)	P <sub>D</sub>	1.5	W	
	(Note 8)		2.0		
	(Note 6)		125		
Thermal Resistance, Junction to Ambient Air	(Note 7)	$R_{\theta JA}$	83	°C/W	
	(Note 8)		60		
Thermal Resistance, Junction to Lead	(Note 9)	$R_{\theta JL}$	13	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C		

### ESD Ratings (Note 10)

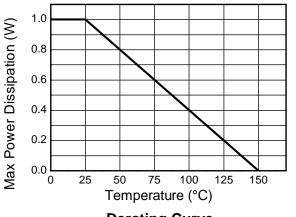
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

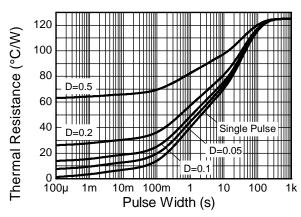
Notes:

- 6. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 7. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
- 8. Same as Note 6, except the device is mounted on 50mm x 50mm 1oz copper.
- 9. Thermal resistance from junction to solder-point (on the exposed collector pad).
- 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



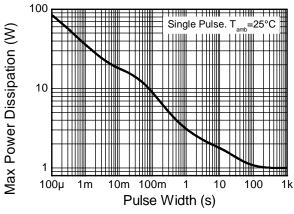
## **Thermal Characteristics and Derating Information**



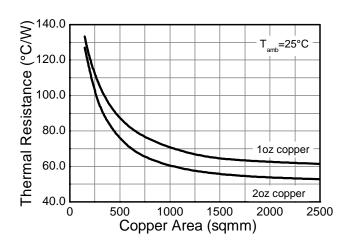


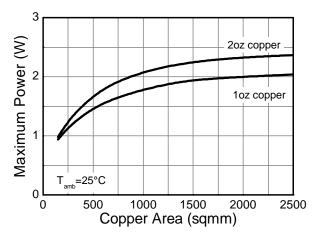
**Derating Curve** 

**Transient Thermal Impedance** 



### **Pulse Power Dissipation**





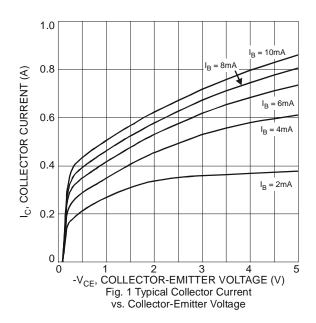


# Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Callaster Dage	BCX51		-45				
Collector-Base Breakdown Voltage	BCX52	BV <sub>CBO</sub>	-60	_	_	V	I <sub>C</sub> = -100μA
Dicardown Voltage	BCX53		-100				
Callastan Fraittan	BCX51		-45	_	_		
Collector-Emitter Breakdown Voltage (Note 11)	BCX52	BV <sub>CEO</sub>	-60			V	$I_C = -10mA$
breakdown voltage (Note 11)	BCX53		-80				
Emitter-Base Breakdown Voltage		BV <sub>EBO</sub>	-5	_	_	V	I <sub>E</sub> = -10μA
Outlies to a Out Off Ourseld		Ісво	_	_	-0.1 -20		V <sub>CB</sub> = -30V
Collector Cut-Oil Current	Collector Cut-Off Current					μA	$V_{CB} = -30V, T_J = +150$ °C
Emitter Cut-Off Current		I <sub>EBO</sub>	_	_	-20	nA	V <sub>EB</sub> = -5V
	All versions		25	_	_	_	$I_C = -5mA$ , $V_{CE} = -2V$
		h <sub>FE</sub>	40	_	250		$I_C = -150 \text{mA}, V_{CE} = -2 \text{V}$
Static Forward Current Transfer Ratio (Note 11)			25	_	_		$I_C = -500 \text{mA}, V_{CE} = -2 \text{V}$
(Note 11)	10 gain grp		63	_	160		$I_C = -150 \text{mA}, V_{CE} = -2 \text{V}$
	16 gain grp		100	_	250		$I_C = -150 \text{mA}, V_{CE} = -2 \text{V}$
Collector-Emitter Saturation Voltage (Note 11)		V <sub>CE(sat)</sub>	_	_	-0.5	V	$I_C = -500 \text{mA}, I_B = -50 \text{mA}$
Base-Emitter Turn-On Voltage (Note 11)		V <sub>BE(on)</sub>	_	_	-1.0	V	$I_C = -500 \text{mA}, V_{CE} = -2 \text{V}$
Transition Frequency		f⊤	150	_	_	MHz	$I_C = -50 \text{mA}, V_{CE} = -10 \text{V}$ f = 100MHz
Output Capacitance		Cobo	_		25	pF	$V_{CB} = -10V$ , $f = 1MHz$

Note:

<sup>11.</sup> Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.



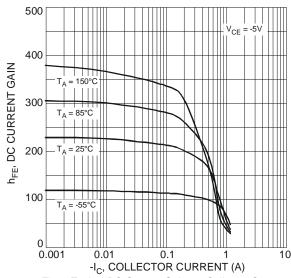


Fig. 2 Typical DC Current Gain vs. Collector Current



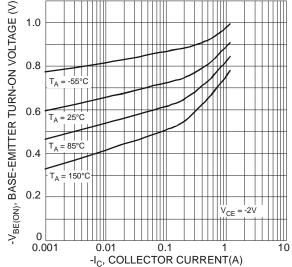


Fig 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

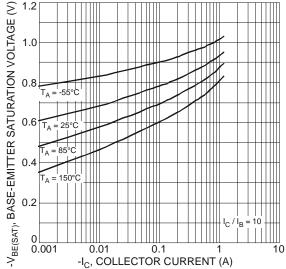


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

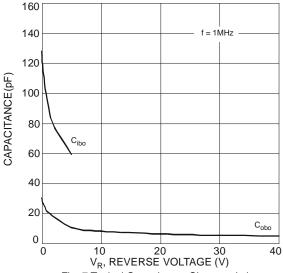


Fig. 7 Typical Capacitance Characteristics

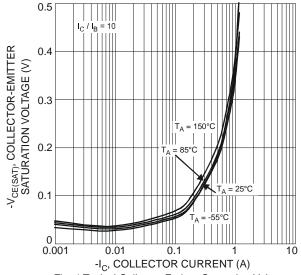


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

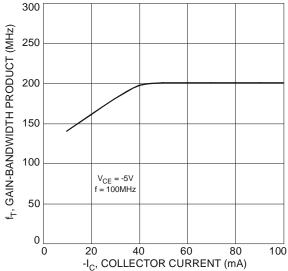
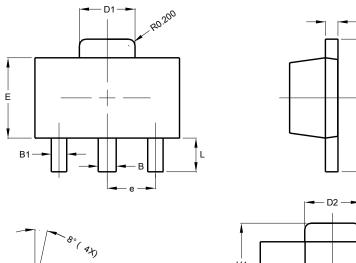


Fig. 6 Typical Gain-Bandwidth Product vs. Collector Current

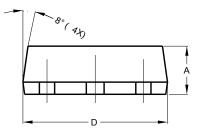


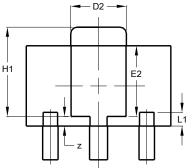
## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



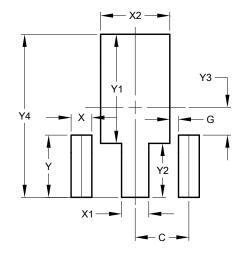
SOT89					
Dim	Min Max		Тур		
Α	1.40	1.60	1.50		
В	0.50	0.62	0.56		
B1	0.42	0.54	0.48		
C	0.35	0.43	0.38		
D	4.40	4.60	4.50		
D1	1.62	1.83	1.733		
D2	1.61	1.81	1.71		
Е	2.40	2.60	2.50		
E2	2.05	2.35	2.20		
e	-	-	1.50		
Η	3.95	4.25	4.10		
H1	2.63	2.93	2.78		
L	0.90	1.20	1.05		
L1	0.327	0.527	0.427		
Z	0.20	0.40	0.30		
All Dimensions in mm					





## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530



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